

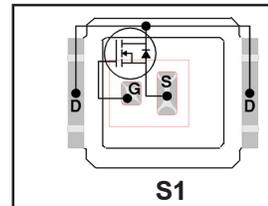
IRF6708S2TRPbF IRF6708S2TR1PbF

DirectFET™ Power MOSFET ②

Typical values (unless otherwise specified)

- RoHS Compliant Containing No Lead and Halogen Free ①
- Low Profile (<0.7 mm)
- Dual Sided Cooling Compatible ①
- Ultra Low Package Inductance
- Optimized for High Frequency Switching ①
- Ideal for CPU Core DC-DC Converters
- Optimized for Control FET Application ①
- Compatible with existing Surface Mount Techniques ①
- 100% R_g tested

| V _{DSS} | V _{GS} | R _{DS(on)} | R _{DS(on)} | | |
|--------------------|-----------------|---------------------|---------------------|------------------|---------------------|
| 30V max | ±20V max | 7.5mΩ@10V | 12mΩ@4.5V | | |
| Q _{g tot} | Q _{gd} | Q _{gs2} | Q _{rr} | Q _{oss} | V _{gs(th)} |
| 6.6nC | 2.2nC | 0.8nC | 14nC | 4.0nC | 1.8V |



Applicable DirectFET Outline and Substrate Outline ①

| | | | | | | | | | | |
|-----------|----|----|--|----|----|--|----|----|----|--|
| S1 | S2 | SB | | M2 | M4 | | L4 | L6 | L8 | |
|-----------|----|----|--|----|----|--|----|----|----|--|

Description

The IRF6708S2TRPbF combines the latest HEXFET® Power MOSFET Silicon technology with the advanced DirectFET™ packaging to achieve improved performance in a package that has the footprint of a MICRO-8 and only 0.7 mm profile. The DirectFET package is compatible with existing layout geometries used in power applications, PCB assembly equipment and vapor phase, infra-red or convection soldering techniques, when application note AN-1035 is followed regarding the manufacturing methods and processes. The DirectFET package allows dual sided cooling to maximize thermal transfer in power systems, improving previous best thermal resistance by 80%.

The IRF6708S2TRPbF has low charge along with ultra low package inductance providing significant reduction in switching losses. The reduced losses make this product ideal for high efficiency DC-DC converters that power the latest generation of processors operating at higher frequencies. The IRF6708S2TRPbF has been optimized for the control FET socket of synchronous buck operating from 12 volt bus converters.

Absolute Maximum Ratings

| | Parameter | Max. | Units |
|--|---|------|-------|
| V _{DS} | Drain-to-Source Voltage | 30 | V |
| V _{GS} | Gate-to-Source Voltage | ±20 | |
| I _D @ T _A = 25°C | Continuous Drain Current, V _{GS} @ 10V ③ | 13 | A |
| I _D @ T _A = 70°C | Continuous Drain Current, V _{GS} @ 10V ③ | 11 | |
| I _D @ T _C = 25°C | Continuous Drain Current, V _{GS} @ 10V ④ | 36 | |
| I _{DM} | Pulsed Drain Current ⑤ | 110 | |
| E _{AS} | Single Pulse Avalanche Energy ⑥ | 53 | mJ |
| I _{AR} | Avalanche Current ⑤ | 10 | A |

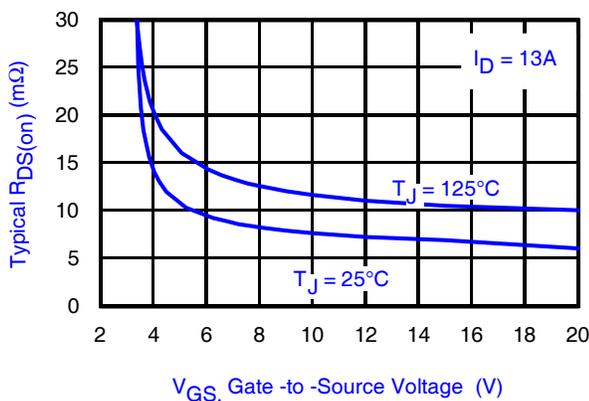


Fig 1. Typical On-Resistance vs. Gate Voltage

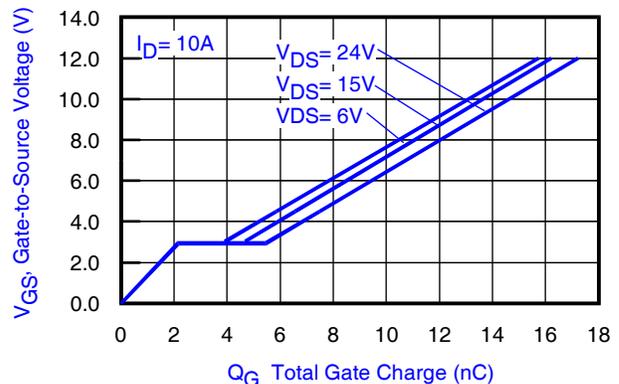


Fig 2. Typical Total Gate Charge vs. Gate-to-Source Voltage

Notes:

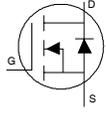
- ① Click on this section to link to the appropriate technical paper.
- ② Click on this section to link to the DirectFET Website.
- ③ Surface mounted on 1 in. square Cu board, steady state.

- ④ T_C measured with thermocouple mounted to top (Drain) of part.
- ⑤ Repetitive rating; pulse width limited by max. junction temperature.
- ⑥ Starting T_J = 25°C, L = 0.976mH, R_G = 50Ω, I_{AS} = 10A.

Static @ T_J = 25°C (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---------------------------------------|---|------|------|------|-------|--|
| BV _{DSS} | Drain-to-Source Breakdown Voltage | 30 | — | — | V | V _{GS} = 0V, I _D = 250μA |
| ΔBV _{DSS} /ΔT _J | Breakdown Voltage Temp. Coefficient | — | 0.02 | — | V/°C | Reference to 25°C, I _D = 1mA |
| R _{DS(on)} | Static Drain-to-Source On-Resistance | — | 7.5 | 8.9 | mΩ | V _{GS} = 10V, I _D = 13A ⑦ |
| | | — | 12 | 14.3 | | V _{GS} = 4.5V, I _D = 10A ⑦ |
| V _{GS(th)} | Gate Threshold Voltage | 1.35 | 1.8 | 2.35 | V | V _{DS} = V _{GS} , I _D = 25μA |
| ΔV _{GS(th)} /ΔT _J | Gate Threshold Voltage Coefficient | — | -7.2 | — | mV/°C | |
| I _{DSS} | Drain-to-Source Leakage Current | — | — | 1.0 | μA | V _{DS} = 24V, V _{GS} = 0V |
| | | — | — | 150 | | V _{DS} = 24V, V _{GS} = 0V, T _J = 125°C |
| I _{GSS} | Gate-to-Source Forward Leakage | — | — | 100 | nA | V _{GS} = 20V |
| | Gate-to-Source Reverse Leakage | — | — | -100 | | V _{GS} = -20V |
| g _{fs} | Forward Transconductance | 22 | — | — | S | V _{DS} = 15V, I _D = 10A |
| Q _g | Total Gate Charge | — | 6.6 | 10 | nC | V _{DS} = 15V V _{GS} = 4.5V I _D = 10A See Fig. 18 |
| Q _{gs1} | Pre-V _{th} Gate-to-Source Charge | — | 1.7 | — | | |
| Q _{gs2} | Post-V _{th} Gate-to-Source Charge | — | 0.8 | — | | |
| Q _{gd} | Gate-to-Drain Charge | — | 2.2 | — | | |
| Q _{godr} | Gate Charge Overdrive | — | 1.9 | — | | |
| Q _{sw} | Switch Charge (Q _{gs2} + Q _{gd}) | — | 3 | — | | |
| Q _{oss} | Output Charge | — | 4 | — | nC | V _{DS} = 10V, V _{GS} = 0V |
| R _G | Gate Resistance | — | 2.5 | — | Ω | |
| t _{d(on)} | Turn-On Delay Time | — | 9.1 | — | ns | V _{DD} = 15V, V _{GS} = 4.5V ⑦ I _D = 10A R _G = 6.2Ω |
| t _r | Rise Time | — | 27 | — | | |
| t _{d(off)} | Turn-Off Delay Time | — | 10 | — | | |
| t _f | Fall Time | — | 11 | — | | |
| C _{iss} | Input Capacitance | — | 1010 | — | pF | V _{GS} = 0V V _{DS} = 15V f = 1.0MHz |
| C _{oss} | Output Capacitance | — | 254 | — | | |
| C _{rss} | Reverse Transfer Capacitance | — | 87 | — | | |

Diode Characteristics

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|-----------------|---|------|------|------|-------|--|
| I _S | Continuous Source Current (Body Diode) | — | — | 25 | A | MOSFET symbol showing the integral reverse p-n junction diode.  |
| I _{SM} | Pulsed Source Current (Body Diode) ⑤ | — | — | 110 | | |
| V _{SD} | Diode Forward Voltage | — | — | 1.0 | V | T _J = 25°C, I _S = 10A, V _{GS} = 0V ⑦ |
| t _{rr} | Reverse Recovery Time | — | 14 | 21 | ns | T _J = 25°C, I _F = 10A |
| Q _{rr} | Reverse Recovery Charge | — | 14 | 21 | nC | di/dt = 200A/μs ⑦ |

Notes:

- ⑤ Repetitive rating; pulse width limited by max. junction temperature.
- ⑦ Pulse width ≤ 400μs; duty cycle ≤ 2%.

Absolute Maximum Ratings

| | Parameter | Max. | Units |
|--------------------------------|----------------------------|--------------|------------------|
| $P_D @ T_A = 25^\circ\text{C}$ | Power Dissipation ③ | 2.5 | W |
| $P_D @ T_A = 70^\circ\text{C}$ | Power Dissipation ③ | 1.8 | |
| $P_D @ T_C = 25^\circ\text{C}$ | Power Dissipation ④ | 20 | |
| T_P | Peak Soldering Temperature | 270 | $^\circ\text{C}$ |
| T_J | Operating Junction and | -55 to + 175 | |
| T_{STG} | Storage Temperature Range | | |

Thermal Resistance

| | Parameter | Typ. | Max. | Units |
|--------------------|--------------------------|------|------|---------------------------|
| $R_{\theta JA}$ | Junction-to-Ambient ③ | — | 60 | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Junction-to-Ambient ⑥ | 12.5 | — | |
| $R_{\theta JA}$ | Junction-to-Ambient ⑨ | 20 | — | |
| $R_{\theta JC}$ | Junction-to-Case ④⑩ | — | 7.6 | |
| $R_{\theta J-PCB}$ | Junction-to-PCB Mounted | 1.0 | — | |
| | Linear Derating Factor ③ | 0.02 | | $\text{W}/^\circ\text{C}$ |

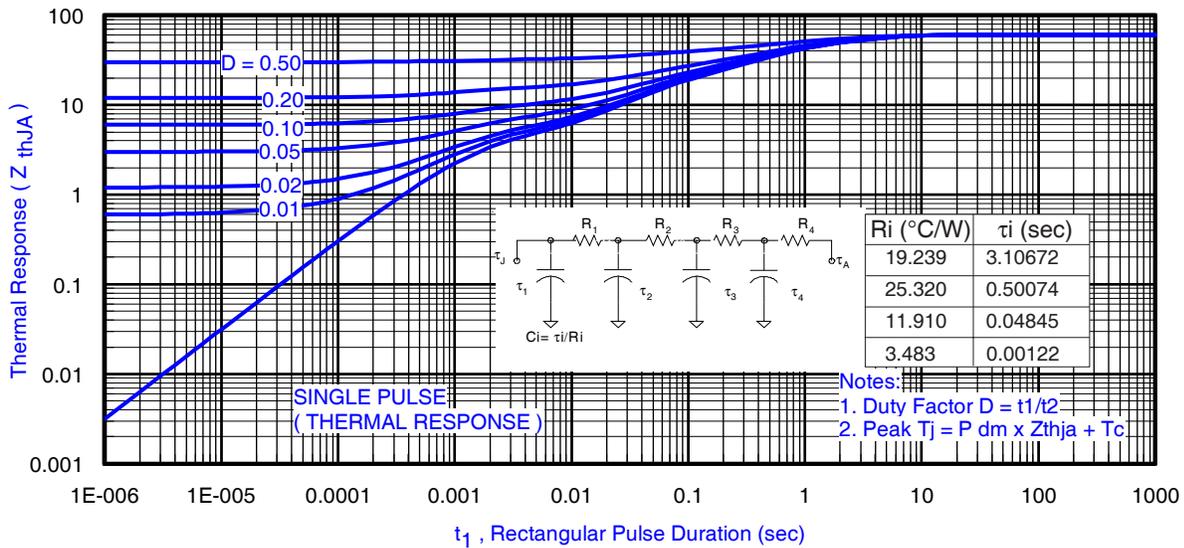
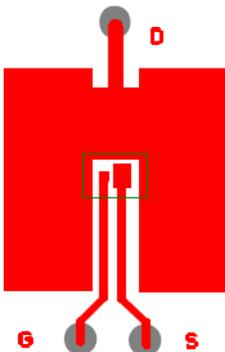


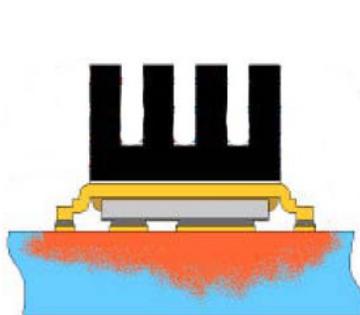
Fig 3. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient ①

Notes:

- ③ Surface mounted on 1 in. square Cu board, steady state.
- ④ T_C measured with thermocouple incontact with top (Drain) of part.
- ⑥ Used double sided cooling, mounting pad with large heatsink.
- ⑨ Mounted on minimum footprint full size board with metalized back and with small clip heatsink.
- ⑩ R_{θ} is measured at T_J of approximately 90°C .



③ Surface mounted on 1 in. square Cu board (still air).



⑨ Mounted on minimum footprint full size board with metalized back and with small clip heatsink. (still air)

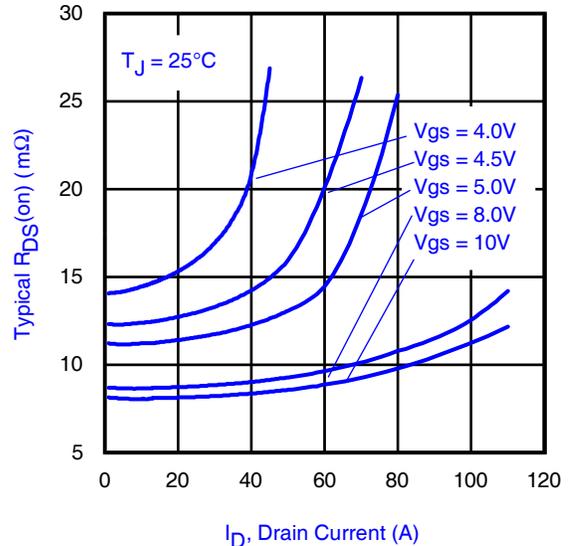
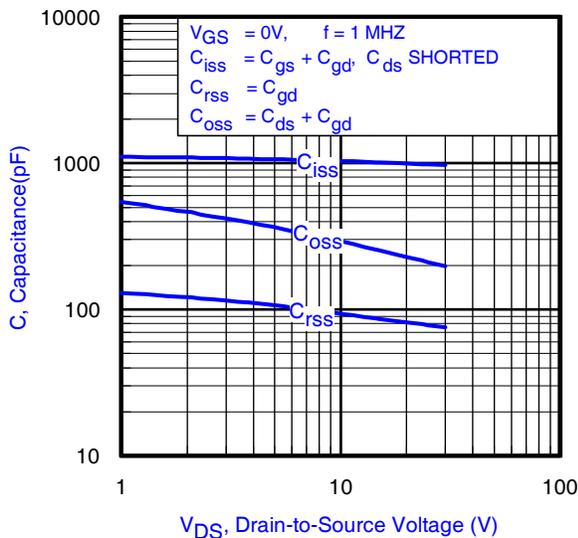
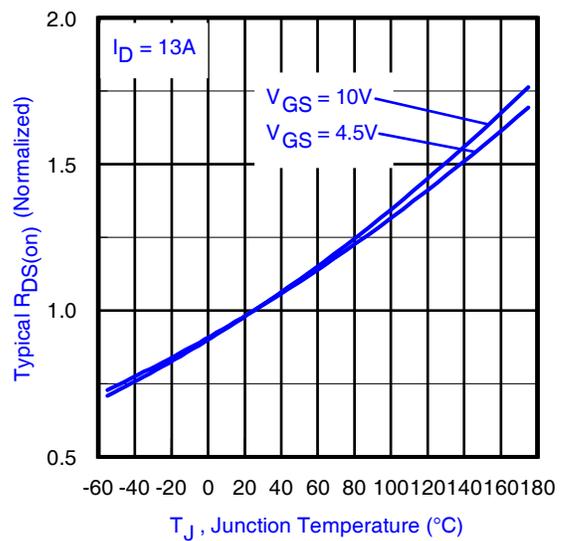
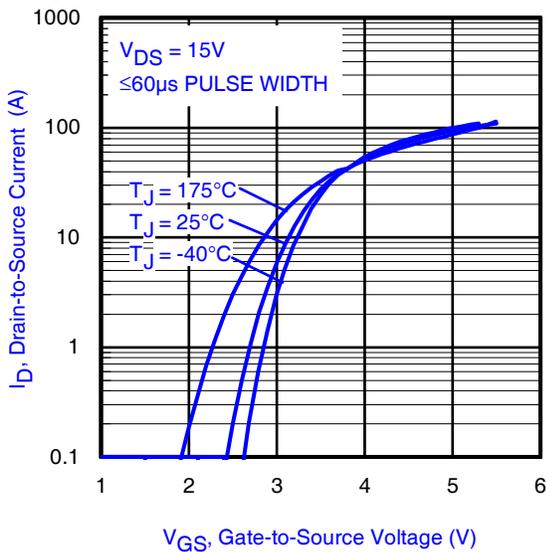
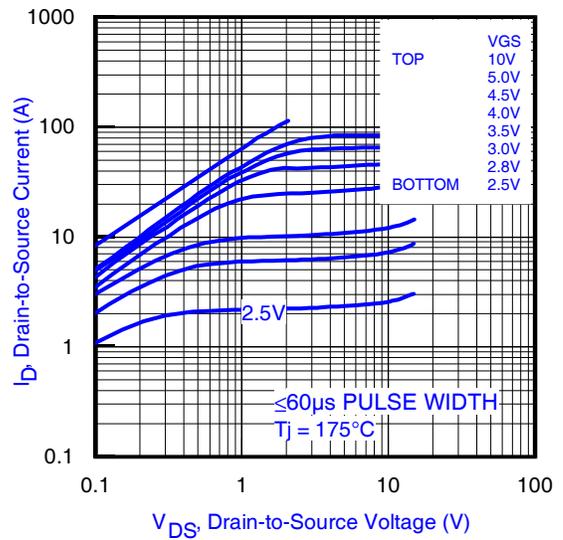
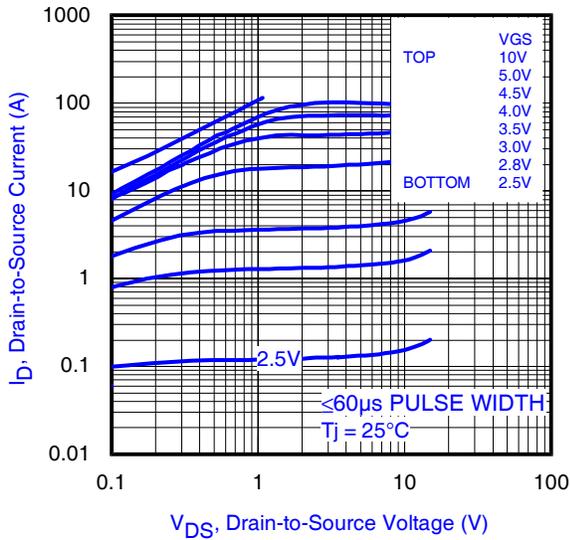


Fig 8. Typical Capacitance vs. Drain-to-Source Voltage

Fig 9. Typical On-Resistance vs. Drain Current and Gate Voltage

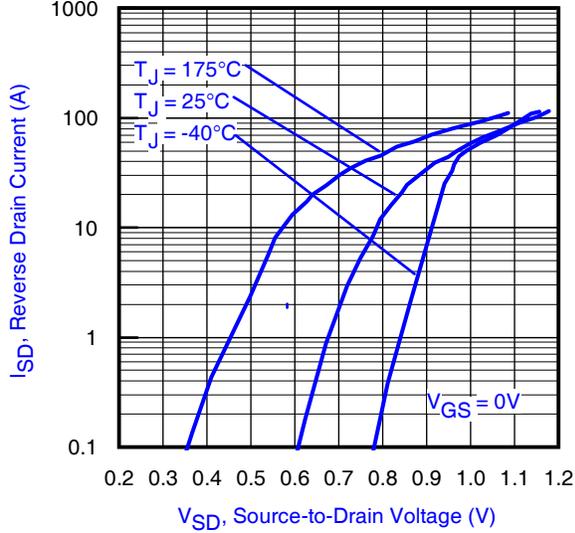


Fig 10. Typical Source-Drain Diode Forward Voltage

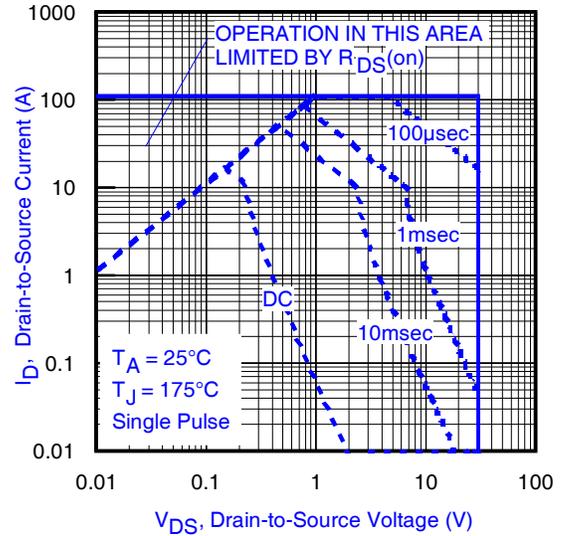


Fig 11. Maximum Safe Operating Area

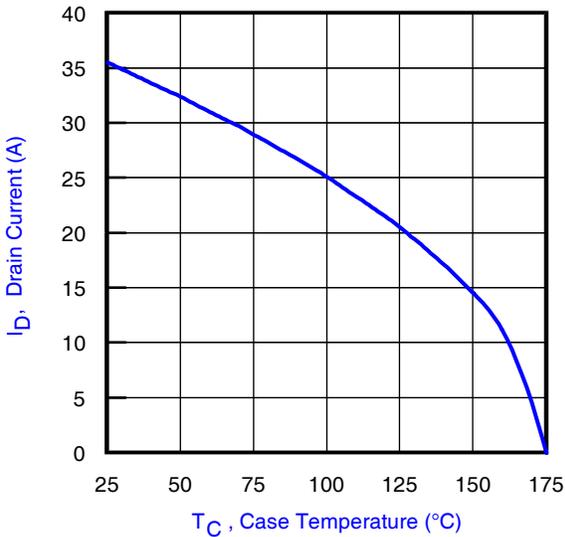


Fig 12. Maximum Drain Current vs. Case Temperature

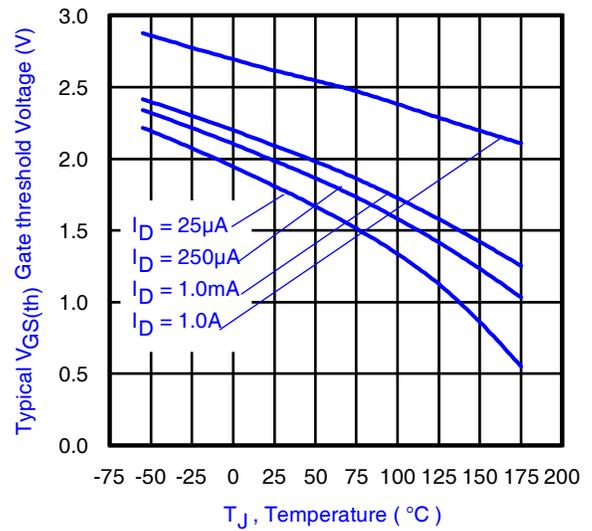


Fig 13. Typical Threshold Voltage vs. Junction Temperature

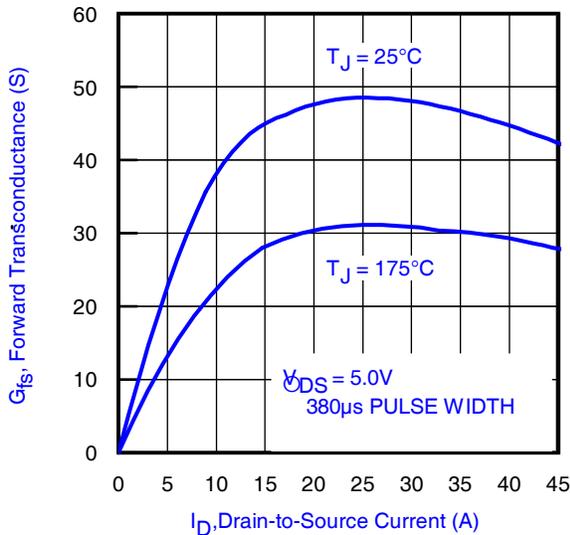


Fig 14. Typ. Forward Transconductance vs. Drain Current
www.irf.com

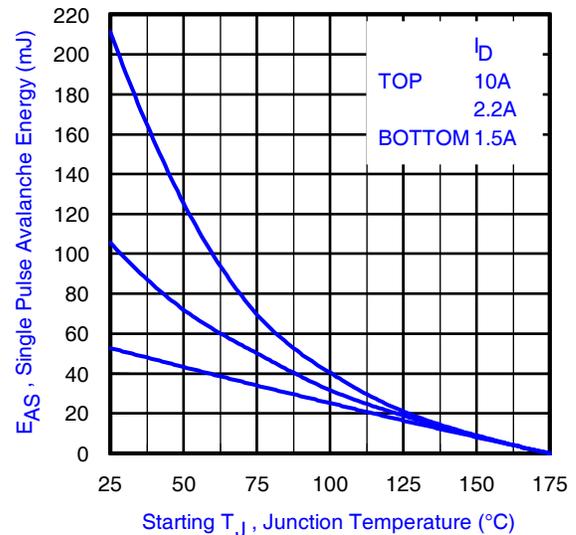


Fig 15. Maximum Avalanche Energy vs. Drain Current

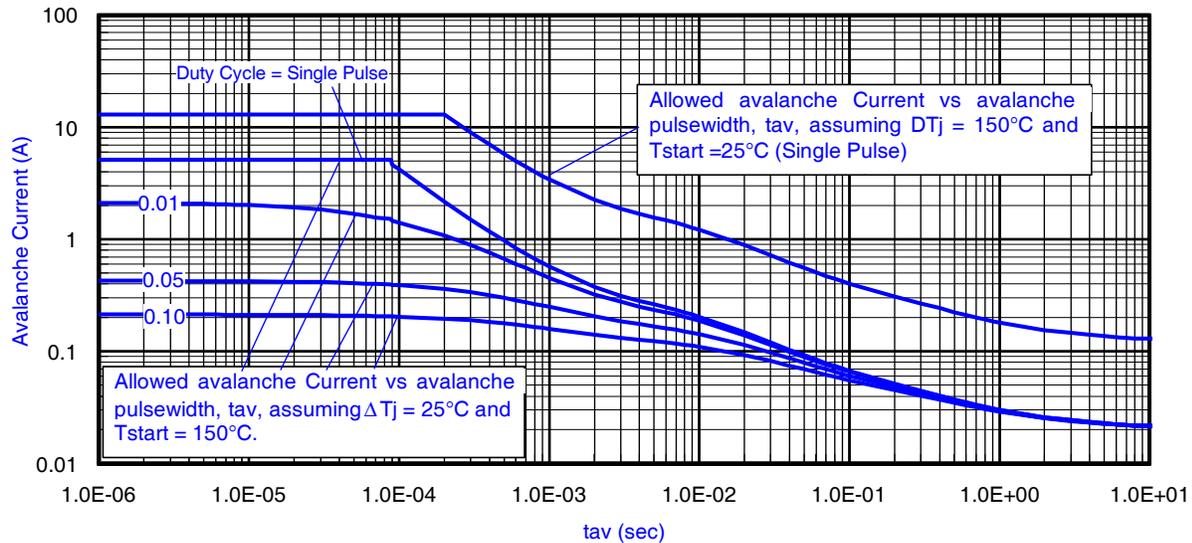


Fig 16. Typical Avalanche Current Vs. Pulsewidth

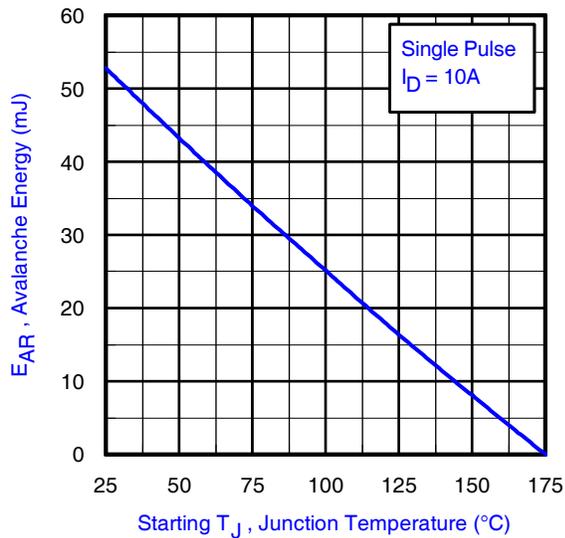


Fig 17. Maximum Avalanche Energy vs. Temperature

Notes on Repetitive Avalanche Curves , Figures 16, 17:
(For further info, see AN-1005 at www.irf.com)

1. Avalanche failures assumption:
Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax} . This is validated for every part type.
2. Safe operation in Avalanche is allowed as long as T_{jmax} is not exceeded.
3. Equation below based on circuit and waveforms shown in Figures 19a, 19b.
4. $P_{D(ave)}$ = Average power dissipation per single avalanche pulse.
5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
6. I_{av} = Allowable avalanche current.
7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 16, 17).
 t_{av} = Average time in avalanche.
 D = Duty cycle in avalanche = $t_{av} \cdot f$
 $Z_{thJC}(D, t_{av})$ = Transient thermal resistance, see figure 11)

$$P_{D(ave)} = 1/2 (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$

$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$

$$E_{AS(AR)} = P_{D(ave)} \cdot t_{av}$$

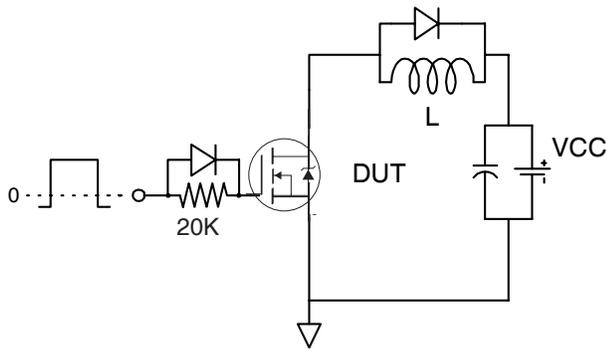


Fig 18a. Gate Charge Test Circuit

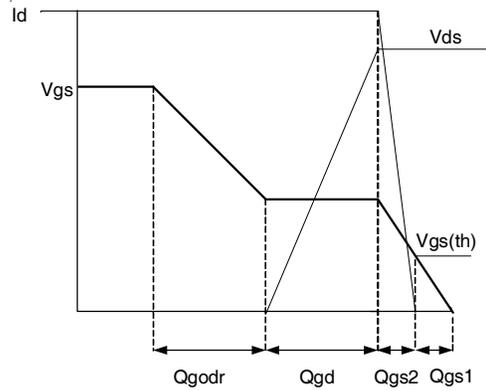


Fig 18b. Gate Charge Waveform

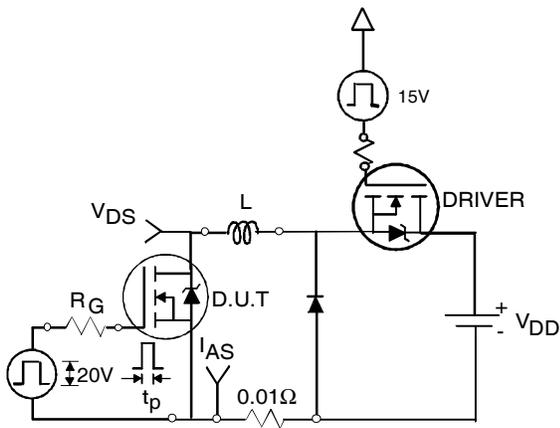


Fig 19a. Unclamped Inductive Test Circuit

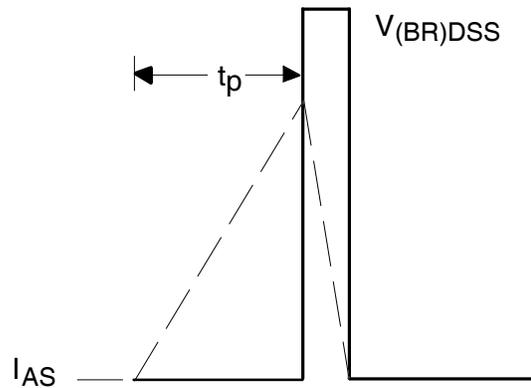


Fig 19b. Unclamped Inductive Waveforms

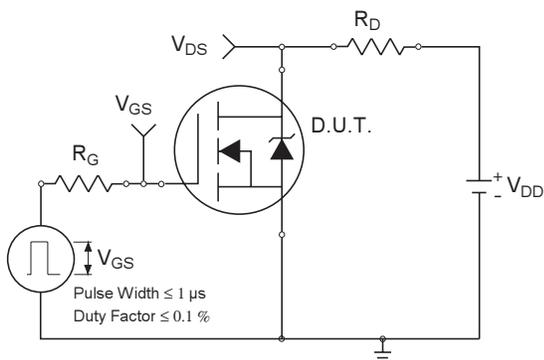


Fig 20a. Switching Time Test Circuit

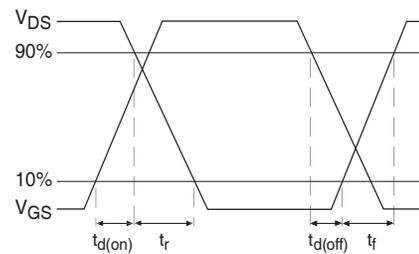


Fig 20b. Switching Time Waveforms

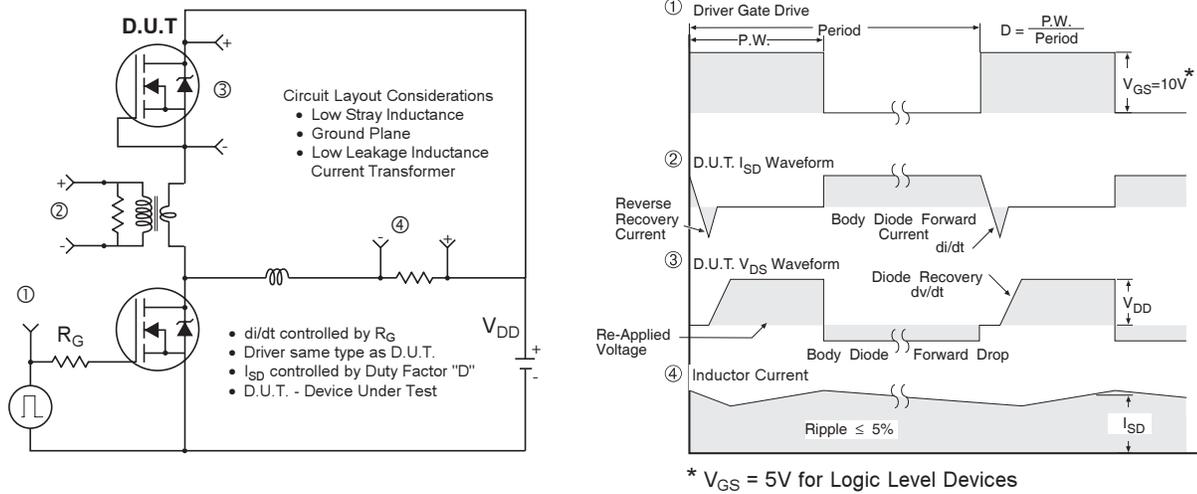
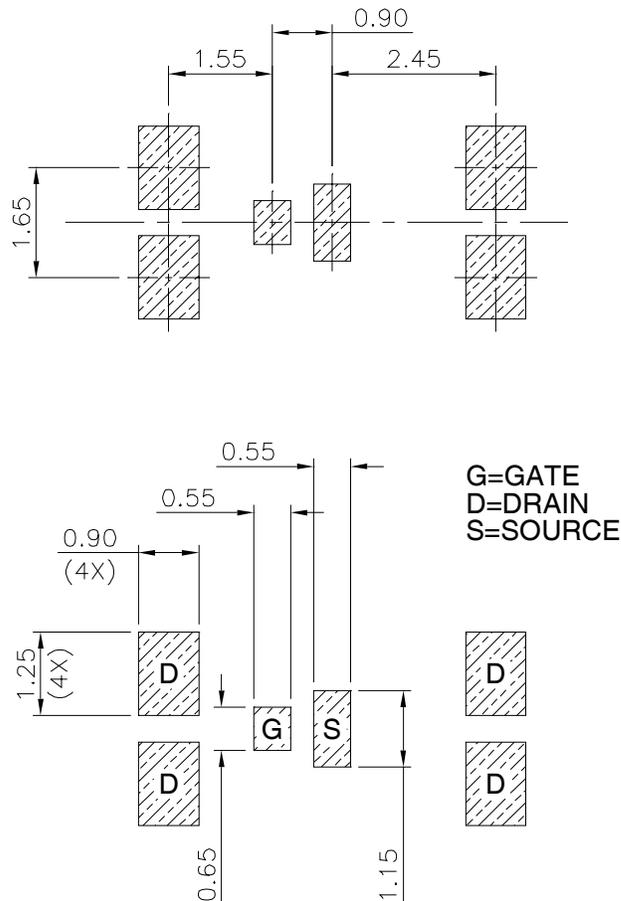


Fig 19. Diode Reverse Recovery Test Circuit for N-Channel HEXFET® Power MOSFETs

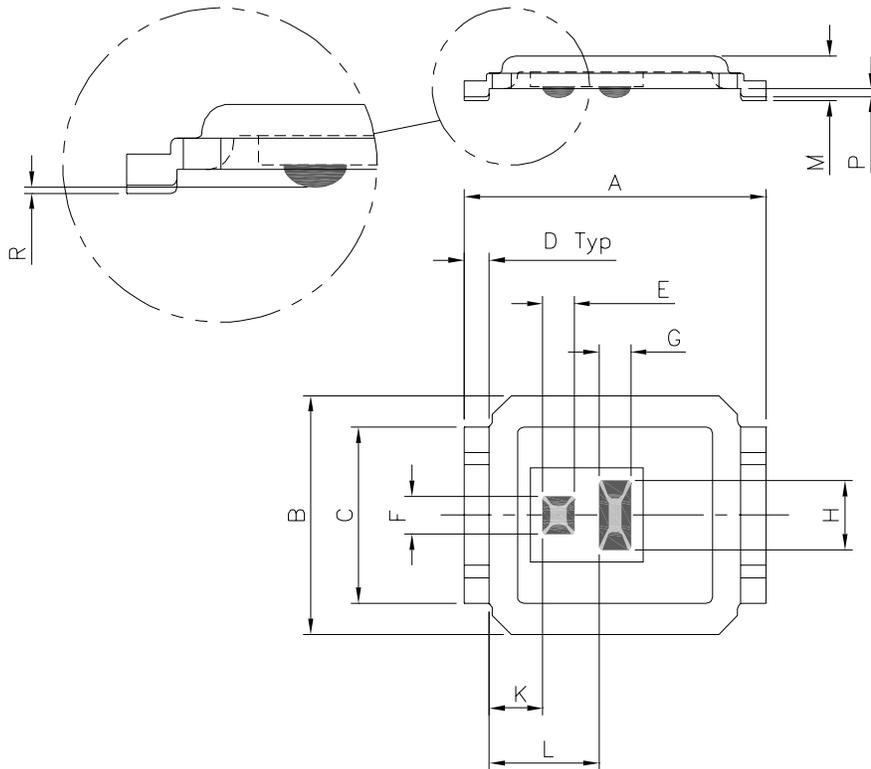
DirectFET™ Board Footprint, S1 (Small Size Can).

Please see AN-1035 for DirectFET assembly details and stencil and substrate design recommendations



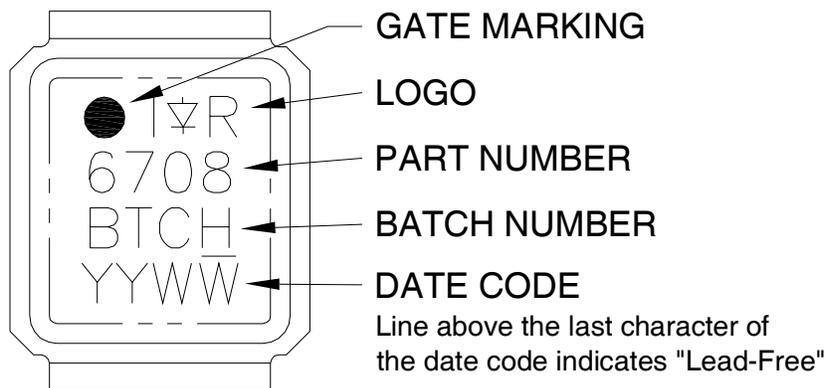
DirectFET™ Outline Dimension, S1 Outline (Small Size Can).

Please see AN-1035 for DirectFET assembly details and stencil and substrate design recommendations



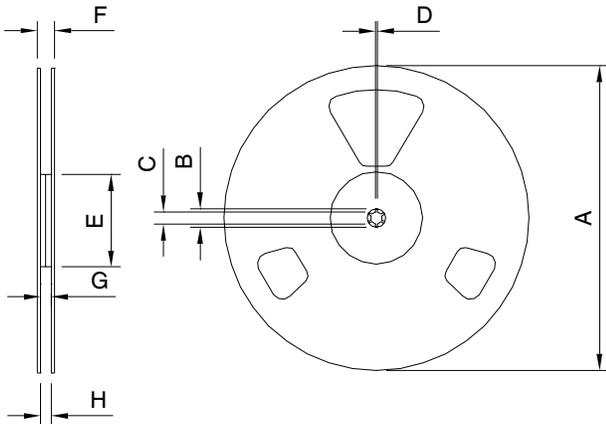
| CODE | DIMENSIONS | | | |
|------|------------|------|----------|-------|
| | METRIC | | IMPERIAL | |
| | MIN | MAX | MIN | MAX |
| A | 4.75 | 4.85 | 0.187 | 0.191 |
| B | 3.70 | 3.95 | 0.146 | 0.156 |
| C | 2.75 | 2.85 | 0.108 | 0.112 |
| D | 0.35 | 0.45 | 0.014 | 0.018 |
| E | 0.48 | 0.52 | 0.019 | 0.020 |
| F | 0.58 | 0.62 | 0.023 | 0.024 |
| G | 0.48 | 0.52 | 0.019 | 0.020 |
| H | 1.08 | 1.12 | 0.043 | 0.044 |
| J | N/A | N/A | N/A | N/A |
| K | 0.80 | 0.90 | 0.031 | 0.035 |
| L | 1.70 | 1.80 | 0.067 | 0.071 |
| M | 0.68 | 0.74 | 0.027 | 0.029 |
| P | 0.08 | 0.17 | 0.003 | 0.007 |
| R | 0.02 | 0.08 | 0.001 | 0.003 |

DirectFET™ Part Marking



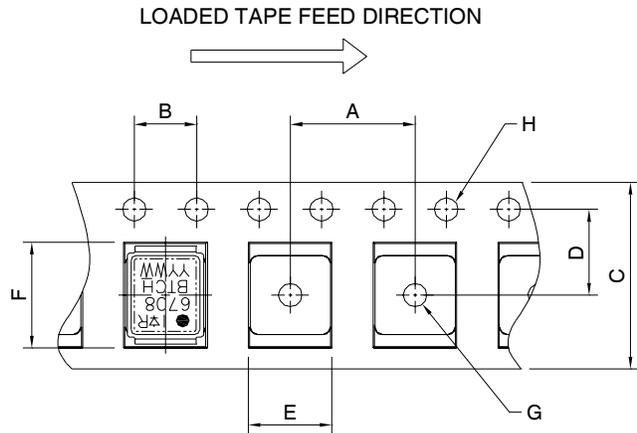
Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>
www.irf.com

DirectFET™ Tape & Reel Dimension (Showing component orientation).



NOTE: Controlling dimensions in mm
Std reel quantity is 4800 parts. (ordered as IRF6708S2TRPBF). For 1000 parts on 7" reel, order IRF6708S2TR1PBF

| REEL DIMENSIONS | | | | | | | |
|-----------------|----------------------------|------|----------|-------|-----------------------|-------|----------|
| CODE | STANDARD OPTION (QTY 4800) | | | | TR1 OPTION (QTY 1000) | | |
| | METRIC | | IMPERIAL | | METRIC | | IMPERIAL |
| A | 330.0 | N.C | 12.992 | N.C | 177.77 | N.C | 6.9 |
| B | 20.2 | N.C | 0.795 | N.C | 19.06 | N.C | 0.75 |
| C | 12.8 | 13.2 | 0.504 | 0.520 | 13.5 | 12.8 | 0.53 |
| D | 1.5 | N.C | 0.059 | N.C | 1.5 | N.C | 0.059 |
| E | 100.0 | N.C | 3.937 | N.C | 58.72 | N.C | 2.31 |
| F | N.C | 18.4 | N.C | 0.724 | N.C | 13.50 | N.C |
| G | 12.4 | 14.4 | 0.488 | 0.567 | 11.9 | 12.01 | 0.47 |
| H | 11.9 | 15.4 | 0.469 | 0.606 | 11.9 | 12.01 | 0.47 |



NOTE: CONTROLLING DIMENSIONS IN MM

| CODE | DIMENSIONS | | | |
|------|------------|-------|----------|-------|
| | METRIC | | IMPERIAL | |
| | MIN | MAX | MIN | MAX |
| A | 7.90 | 8.10 | 0.311 | 0.319 |
| B | 3.90 | 4.10 | 0.154 | 0.161 |
| C | 11.90 | 12.30 | 0.469 | 0.484 |
| D | 5.45 | 5.55 | 0.215 | 0.219 |
| E | 5.10 | 5.30 | 0.201 | 0.209 |
| F | 6.50 | 6.70 | 0.256 | 0.264 |
| G | 1.50 | N.C | 0.059 | N.C |
| H | 1.50 | 1.60 | 0.059 | 0.063 |

Data and specifications subject to change without notice.
This product has been designed and qualified to MSL1 rating for the Consumer market.
Additional storage requirement details for DirectFET products can be found in application note AN1035 on IR's Web site.
Qualification Standards can be found on IR's Web site.

Mouser Electronics

Authorized Distributor

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